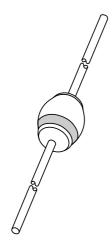
DISCRETE SEMICONDUCTORS

DATA SHEET



BYX10G Rectifier

Product specification

1996 May 24





Rectifier BYX10G

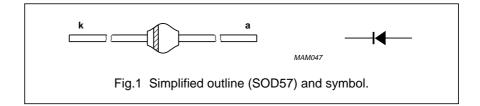
FEATURES

- · Glass passivated
- High maximum operating temperature
- · Low leakage current
- Excellent stability
- Available in ammo-pack.

DESCRIPTION

Rugged glass package, using a high temperature alloyed construction.

This package is hermetically sealed and fatigue free as coefficients of expansion of all used parts are matched.



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

| SYMBOL | PARAMETER | CONDITIONS | MIN. | MAX. | UNIT |
|--------------------|-------------------------------------|--|------|------|------|
| V _{RSM} | non-repetitive peak reverse voltage | | _ | 1600 | ٧ |
| V_{RRM} | repetitive peak reverse voltage | | _ | 1600 | V |
| V_{RWM} | crest working reverse voltage | | _ | 800 | V |
| I _{F(AV)} | average forward current | T _{tp} = 50 °C; lead length = 10 mm; averaged over any 20 ms period; see Figs 2 and 4 | _ | 1.2 | Α |
| | | T _{amb} = 60 °C; PCB mounting (see Fig.9); averaged over any 20 ms period; see Figs 3 and 4 | _ | 0.6 | A |
| I _{FSM} | non-repetitive peak forward current | t = 10 ms half sinewave; $T_j = T_{j max}$ prior to surge; $V_R = V_{RWMmax}$ | _ | 25 | А |
| T _{stg} | storage temperature | | -65 | +175 | °C |
| Tj | junction temperature | see Fig.5 | -65 | +175 | °C |

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ELECTRICAL CHARACTERISTICS

 T_j = 25 °C; unless otherwise specified.

| SYMBOL | PARAMETER | CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|-----------------|-----------------------|---|------|------|------|------|
| V _F | forward voltage | $I_F = 2 \text{ A}; T_j = T_{j \text{ max}}; \text{ see Fig.6}$ | _ | _ | 1.5 | V |
| | | I _F = 2 A; see Fig.6 | _ | _ | 1.5 | V |
| I _R | reverse current | V _R = V _{RWMmax} ; see Fig.7 | _ | _ | 1 | μΑ |
| | | V _R = V _{RWMmax} ; T _j = 150 °C; see Fig.7 | _ | _ | 200 | μΑ |
| t _{rr} | reverse recovery time | when switched from $I_F = 0.5$ A to $I_R = 1$ A; measured at $I_R = 0.25$ A; see Fig.10 | _ | 3 | _ | μs |
| C _d | diode capacitance | V _R = 0 V; f = 1 MHz; see Fig.8 | _ | 30 | _ | pF |

THERMAL CHARACTERISTICS

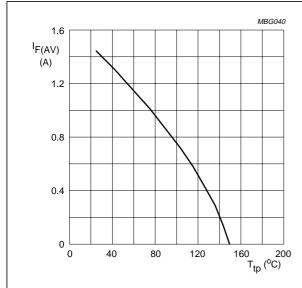
| SYMBOL | PARAMETER | CONDITIONS | VALUE | UNIT |
|----------------------|---|---------------------|-------|------|
| R _{th j-tp} | thermal resistance from junction to tie-point | lead length = 10 mm | 46 | K/W |
| R _{th j-a} | thermal resistance from junction to ambient | note 1 | 100 | K/W |

Note

1. Device mounted on epoxy-glass printed-circuit board, 1.5 mm thick; thickness of copper \geq 40 μ m, see Fig.9. For more information please refer to the "General Part of associated Handbook".

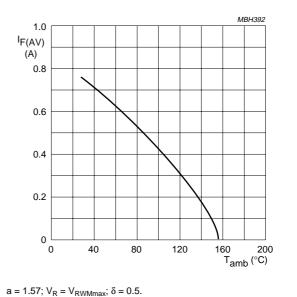
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GRAPHICAL DATA



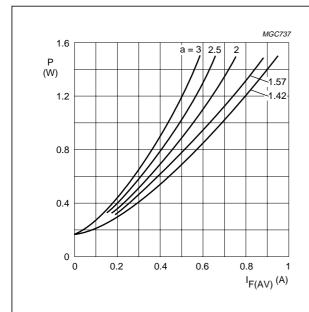
a = 1.57; $V_R = V_{RWMmax}$; $\delta = 0.5$. Lead length 10 mm.

Maximum permissible average forward current as a function of tie-point temperature (including losses due to reverse leakage).



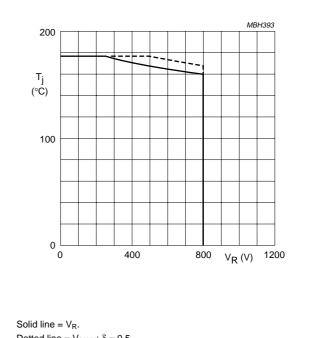
Device mounted as shown in Fig.9.

Maximum permissible average forward current as a function of ambient temperature (including losses due to reverse leakage).



 $a = I_{F(RMS)}/I_{F(AV)}; \ V_R = V_{RWMmax}; \ \delta = 0.5.$

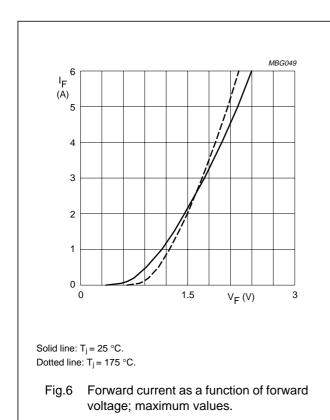
Maximum steady state power dissipation (forward plus leakage current losses, excluding switching losses) as a function of average forward current.



Dotted line = V_{RWM} ; δ = 0.5.

Fig.5 Maximum permissible junction temperature as a function of reverse voltage.

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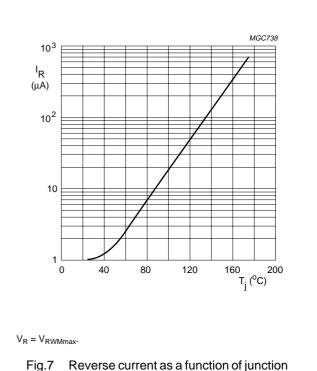
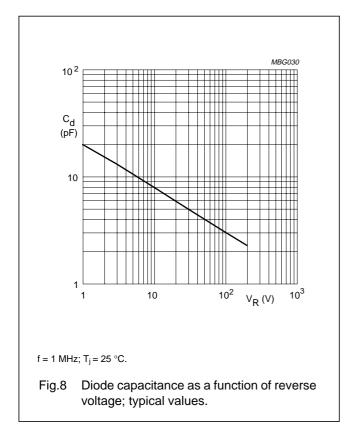
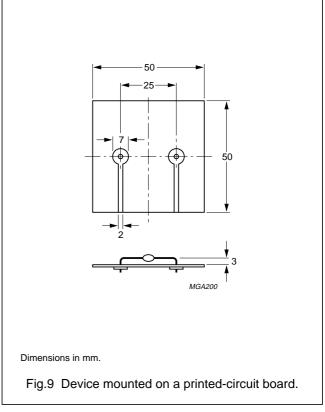


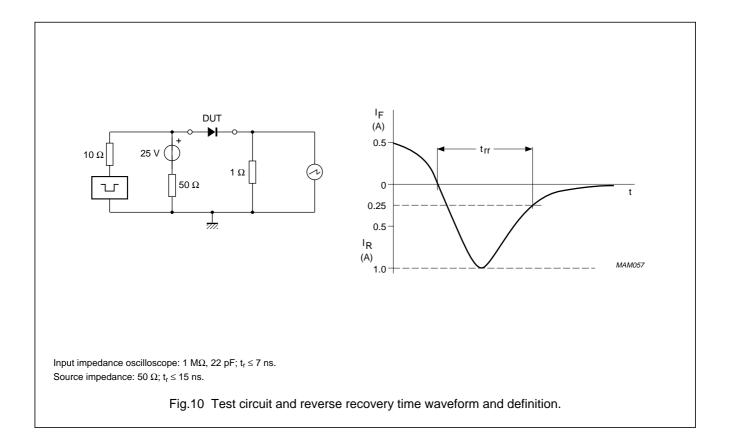
Fig.7 Reverse current as a function of junction temperature; maximum values.





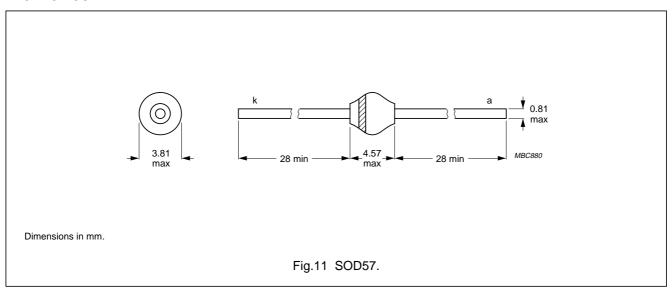
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PACKAGE OUTLINE



DEFINITIONS

| Data sheet status | |
|---------------------------|---|
| Objective specification | This data sheet contains target or goal specifications for product development. |
| Preliminary specification | This data sheet contains preliminary data; supplementary data may be published later. |
| Product specification | This data sheet contains final product specifications. |
| Limitim manalana | |

Limiting values

Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.